

CE DECLARATION OF PERFORMANCE

According to Regulation (EU) No. 305 of the European Parliament and the Council of 9 March 2011

DOP No	DOP-225
1 Unique identification product code	Egger Eurospan EAC E1 P5/Protect CE Code: 225 8 to 40 mm (board thickness)
2 Intended use	Chipboard P5 (EN312) for internal use as a structural component in humid conditions
3 Manufacturer	EGGER group – Fritz EGGER GmbH & Co. OG Weiberndorf 20 A-6380 St. Johann/Tyrol, Austria web: www.egger.com
4 not applicable	
5 System of assessment and verification of constancy of performance	System 2+
6 Harmonised standard	EN 13986:2004+A1:2015
Notified body	0380 Institut Technologique FCBA 10, Rue Galilée 77420 Champs-sur-Mame France the certification and has issued the certificate 0380-CPR-0366

7 Declaration of performance/s

Essential characteristics *1	Unit	8 -13	13 -20	20 - 25	25 - 32	32 - 40	Harmonised technical specification	
Board thickness	mm							EN13986:2004+A1:2015
Strength								
Tension	N/mm ²	-	8.5	7.4	6.6	5.6		
Compression	N/mm ²	-	11.8	10.3	9.8	8.5		
Bending	N/mm ²	-	13.3	11.7	10.0	8.3		
Panel shear	N/mm ²	-	6.5	5.9	5.2	4.8		
Planar shear	N/mm ²	-	1.7	1.5	1.3	1.2		
Stiffness (MOE)								
Tension and Compression	N/mm ²	-	1900	1800	1500	1400		
Bending	N/mm ²	-	3300	3000	2600	2400		
Panel shear	N/mm ²	-	930	860	750	690		
Punching shear as point load strength and point load stiffness		NPD						
Impact resistance: (acc. to EN 12871)		Pass						
Bending strength	N/mm ²	18	16	14	12	10		
Internal bond	N/mm ²	0.45	0.45	0.40	0.35	0.30		
Bending modulus of elasticity	N/mm ²	2550	2400	2150	1900	1700		
Thickness swelling 24h	%	11	10	10	10	9		
Swelling in thickness after cyclic test EN 321	%	12	12	11	10	9		
Internal bond after cyclic test	N/mm ²	0.25	0.22	0.20	0.17	0.15		
Formaldehyde emission class		E1						
Reaction to fire *2 Without air gap behind the board		E	D-s2, d0	D-s2, d0	D-s2, d0	D-s2, d0		
With or without air gap ≤ 22 mm behind the board		E	D-s2, d2	D-s2, d2	D-s2, d2	D-s2, d2		
Without air gap > 22 mm behind the board		E	E	D-s2, d0	D-s2, d0	D-s2, d0		
With air gap > 22 mm behind the board		E	E	D-s2, d0	D-s2, d0	D-s2, d0		
Water vapour permeability								
wet	μ	15						
dry	μ	50						
Airborne sound insulation		NPD						
Sound absorption	α	0.10 / 0.25						
Thermal conductivity	W/mK	0.12						
Biological durability		1						
Content of PCP	ppm	< 5						

*1 Essential characteristics are valid for following plant/s of the EGGER Group:

- 27 EGGER (UK) Limited
Anick Grange Road, Hexham
NE46 4JS
United Kingdom

*2 Density ≥ 600 kg/m³

8 not applicable

The performance of the product identified above is in conformity with the set of declared performance/s. This declaration of performance is issued, in accordance with Regulation (EU) No 305/2011, under the sole responsibility of the manufacturer identified above.

Signed for and on behalf of the manufacturer by

St. Johann / Tyrol 18.07.2019

A handwritten signature in black ink, appearing to read "Manfred Riepertinger".

Manfred Riepertinger

Core Material Management / Product Sustainability
Group